Special Issue

New Aspects of Si-Based Material and Device

Message from the Guest Editor

For more than half a century, Si-based materials and devices have been utilized and mass-produced for a wide range of uses including microprocessors and memory technologies thanks to high-quality silicon dioxide and cost-effectiveness. Alternative semiconductor materials have been investigated to replace Si as the end of Moore’s law is approaching, however, it is still important to understand fundamental material properties of Si and develop Si-based devices in order to provide novel breakthrough approaches to overcome the physical limits of current ICs and present their feasibility with the mature Si technology platform. This special issue is devoted to highlight pioneering research papers, rapid communications, and review articles on Si-based materials and devices for advanced semiconductor technologies.

Guest Editor

Dr. Hyungjin Kim
Department of Electronic Engineering, Inha University, Incheon 22212, Republic of Korea

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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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